

ETCH RESIST USING PRINTER TECHNOLOGY

ABSTRACT

[00021] The present invention provides a printer and an inexpensive method for producing a printed circuit board using a printer configured to facilitate printing at least directly on a copper-clad substrate. The method includes the steps of feeding a copper-clad substrate into the printer, printing an inverse circuit image on the copper-clad substrate, allowing the inverse circuit image to dry, metalizing the copper-clad substrate to adhere a resist mask to exposed, uninked copper to form a metalized circuit image, and etching the copper-clad substrate that has been metalized to remove copper that forms the inverse circuit image.